International Rectifier

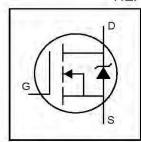
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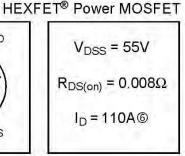
- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead-Free

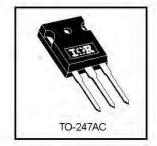
Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting







Absolute Maximum Ratings

	Parameter	Max.	Units	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	110©		
ID @ TC = 100°C	Continuous Drain Current, VGS @ 10V	80©	A	
Гом	Pulsed Drain Current ①⑤	390		
P _D @T _C =25°C	Power Dissipation	200	W	
	Linear Derating Factor	1.3	W/°C	
V _{GS}	Gate-to-Source Voltage	± 20	V	
EAS	Single Pulse Avalanche Energy@®	480	mJ	
lar.	Avalanche Current®	59	A	
EAR	Repetitive Avalanche Energy®	20	mJ	
dv/dt	Peak Diode Recovery dv/dt 35	5.0	V/ns	
TJ	Operating Junction and	-55 to + 175		
T _{STG}	Storage Temperature Range		°C	
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	-	
	Mounting torque, 6-32 or M3 srew	10 lbf•in (1.1N•m)		

Thermal Resistance

	Parameter	Тур.	Max.	Units	
R _{0,C}	Junction-to-Case		0.75	°C/W	
R _{0CS}	Case-to-Sink, Flat, Greased Surface	0.24			
Raja	Junction-to-Ambient		40		

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

-	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	55	—		V	$V_{GS} = 0V, I_{D} = 250\mu A$
ΔV _{(BR)DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient		0.057		V/°C	Reference to 25°C, ID = 1mA®
R _{DS(on)}	Static Drain-to-Source On-Resistance	_		0.008	Ω	V _{GS} = 10V, I _D = 59A ⊕
VGS(th)	Gate Threshold Voltage	2.0		4.0	V	V _{DS} = V _{GS} , I _D = 250µA
g _{fs}	Forward Transconductance	42			S	V _{DS} = 25V, I _D = 59A ⑤
li rata	Drain-to-Source Leakage Current	-		25		$V_{DS} = 55V, V_{GS} = 0V$
IDSS	Dialific-Source Leakage Current	-		250	μA	V _{DS} = 44V, V _{GS} = 0V, T _J = 150°C
	Gate-to-Source Forward Leakage			100	nA	V _{GS} = 20V
GSS	Gate-to-Source Reverse Leakage	-	-	-100		V _{GS} = -20V
Qq	Total Gate Charge	-		170	nC	I _D = 59A V _{DS} = 44V V _{GS} = 10V, See Fig. 6 and 13 ⊕ ⑤
Q _{gs}	Gate-to-Source Charge	-	<u>,</u> ,	32		
Q _{gd}	Gate-to-Drain ("Miller") Charge		_	74		
t _{d(on)}	Turn-On Delay Time	×	14			V_{DD} = 28V I_D = 59A R_G = 2.5Ω R_D = 0.39Ω, See Fig. 10 \odot
tr	Rise Time		100			
t _{d(aff)}	Turn-Off Delay Time	-	43		ns	
tf	Fall Time		70			
L _D	Internal Drain Inductance		5.0		'nН	Between lead, 6mm (0.25in.) from package and center of die contact
Ls	Internal Source Inductance	-	13	-		
Ciss	Input Capacitance		4000		pF	V _{GS} = 0V V _{DS} = 25V
Coss	Output Capacitance		1300	-		
Crss	Reverse Transfer Capacitance		480			f = 1.0MHz, See Fig. 5®

Source-Drain Ratings and Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
Is	Continuous Source Current (Body Diode)			110®		MOSFET symbol showing the
Ism	Pulsed Source Current (Body Diode) ①			390		integral reverse p-n junction diode.
V _{SD}	Diode Forward Voltage	11		1.3	V	T _J = 25°C, I _S = 59A, V _{GS} = 0V •
t _{ir}	Reverse Recovery Time		110	170	ns	T _J = 25°C, I _F = 59A
Qm	Reverse Recovery Charge	- 1	450	680	nC	di/dt = 100A/µs ⊕⑤

Notes:

- Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- $V_{DD} = 25V$, starting $T_J = 25$ °C, $L = 190 \mu H$ $R_G = 25Ω$, $I_{AS} = 59A$. (See Figure 12)
- $\ \ \ I_{SD} \leq 59A, \ di/dt \leq 290A/\mu s, \ V_{DD} \leq V_{(BR)DSS}, \ T_{J} \leq 175^{\circ}C$
- 9 Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.
- (3) Uses IRF3205 data and test conditions
- © Caculated continuous current based on maximum allowable junction temperature; for recommended current-handling of the package refer to Design Tip # 93-4

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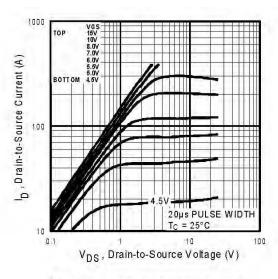


Fig 1. Typical Output Characteristics

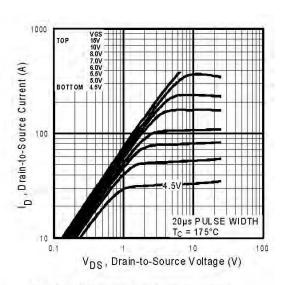


Fig 2. Typical Output Characteristics

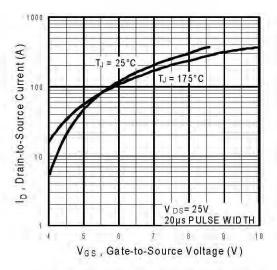


Fig 3. Typical Transfer Characteristics

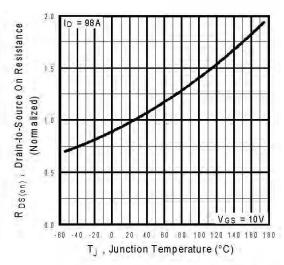


Fig 4. Normalized On-Resistance Vs. Temperature

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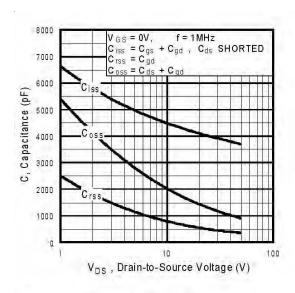
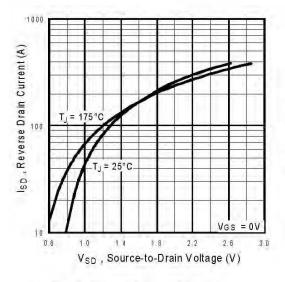


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage



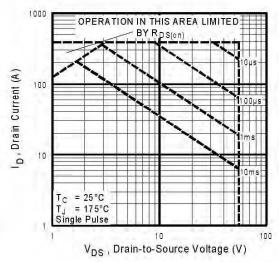


Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area

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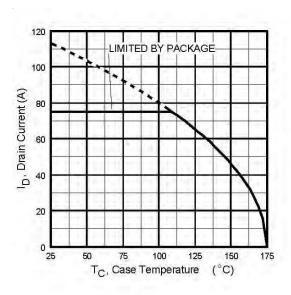


Fig 9. Maximum Drain Current Vs. Case Temperature

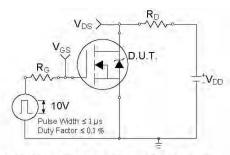


Fig 10a. Switching Time Test Circuit

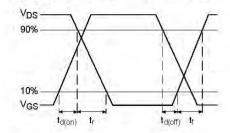


Fig 10b. Switching Time Waveforms

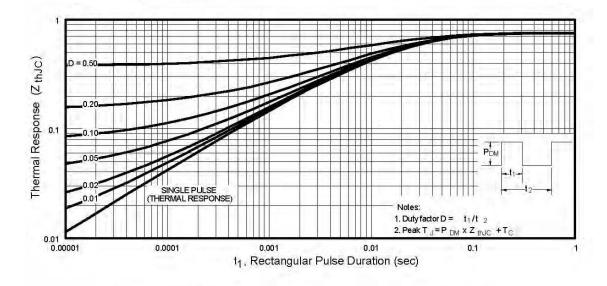


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

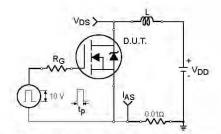


Fig 12a. Unclamped Inductive Test Circuit

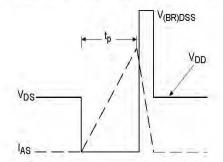


Fig 12b. Unclamped Inductive Waveforms

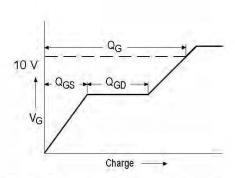


Fig 13a. Basic Gate Charge Waveform

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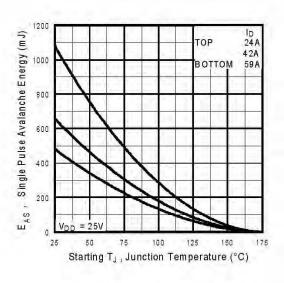


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

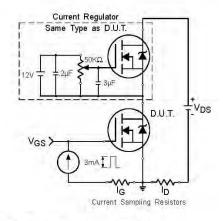


Fig 13b. Gate Charge Test Circuit

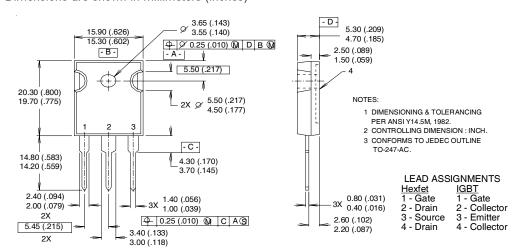
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Peak Diode Recovery dv/dt Test Circuit Circuit Layout Considerations D.U.T · Low Stray Inductance Ground Plane Low Leakage Inductance Current Transformer dv/dt controlled by R_G Driver same type as D.U.T. VDD I_{SD} controlled by Duty Factor "D" D.U.T. - Device Under Test ① Driver Gate Drive $D = \frac{P.W.}{Period}$ P.W. V_{GS}=10V * D.U.T. I_{SD} Waveform Reverse Recovery Current Body Diode Forward Diode ro... Current di/dt ③ D.U.T. V_{DS} Waveform Diode Recovery dv/dt VDD Re-Applied Voltage Body Diode Forward Drop 4 Inductor Curent Ripple ≤ 5% I_{SD} * V_{GS} = 5V for Logic Level Devices Fig 14. For N-Channel HEXFETS

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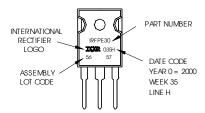
TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



TO-247AC Part Marking Information





Data and specifications subject to change without notice.



IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105 TAC Fax: (310) 252-7903

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Note: For the most current drawings please refer to the IR website at: http://www.irf.com/package/

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